

* Interconnections (↔) are implemented via AXI Interfaces.

* PS has fixed architecture and hosts processor & system memory

* PS completely flexible, we can create custom peripherals (or) reuse standard ones.

Peripherals:

- * functional components residing away from processors
- * need to be connected if you want to use.

* 3 main functions:

- 1) Co-processors (e.g. DMA)
- 2) Interacting with external blocks (e.g. led, switch, sensor)
- 3) additional memory elements

Industry Standard front

Pack into IP blocks

reusable blocks

* IPs corresponds to peripheral components

Contain dual-core ARM Cortex A9 Processor

PS →

"Hard processor" } Has dedicated and optimised silicon element on the device

"Soft processor" } formed by combining clunks of the PL fabric.

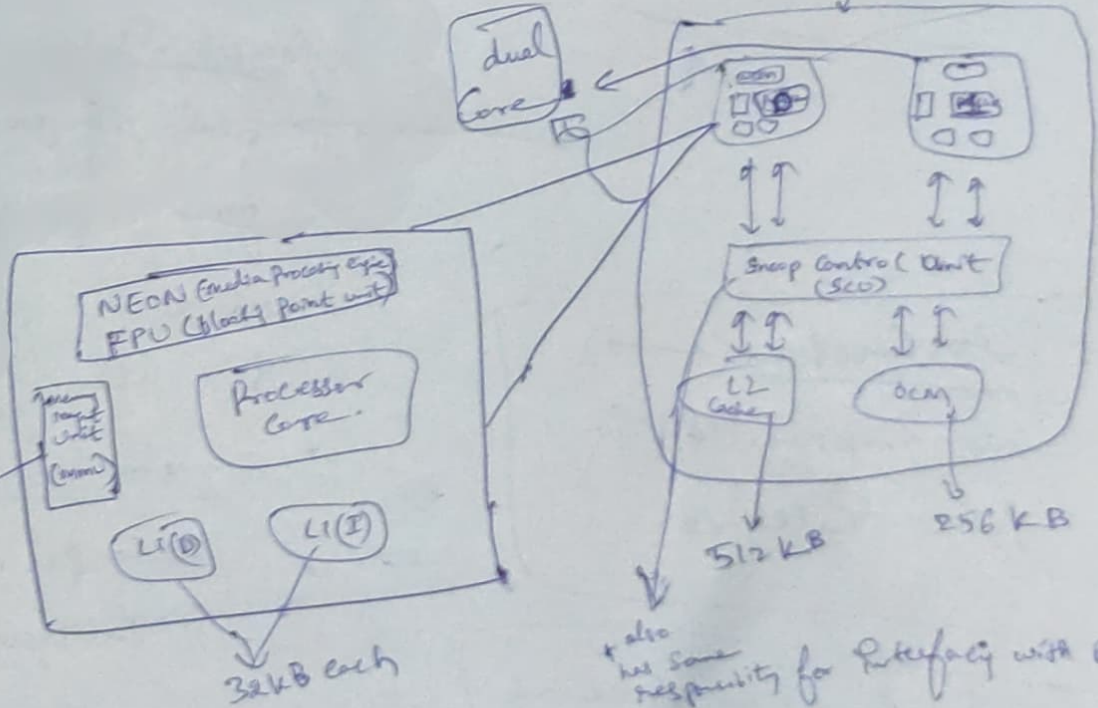
Ex: nips, microBlaze
~~Intel~~ Xilinx

Advantage is that we can use multiple instances of a soft processor

* * We can use & connect b/w both soft processor & hard processor.

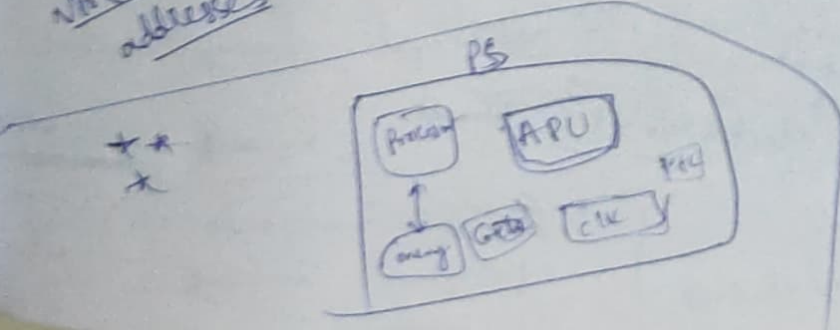
* PS is not just ARM processor it also has Set of Processing resources
 peripheral interfaces, cache, many interfaces, interconnect, clk, etc.

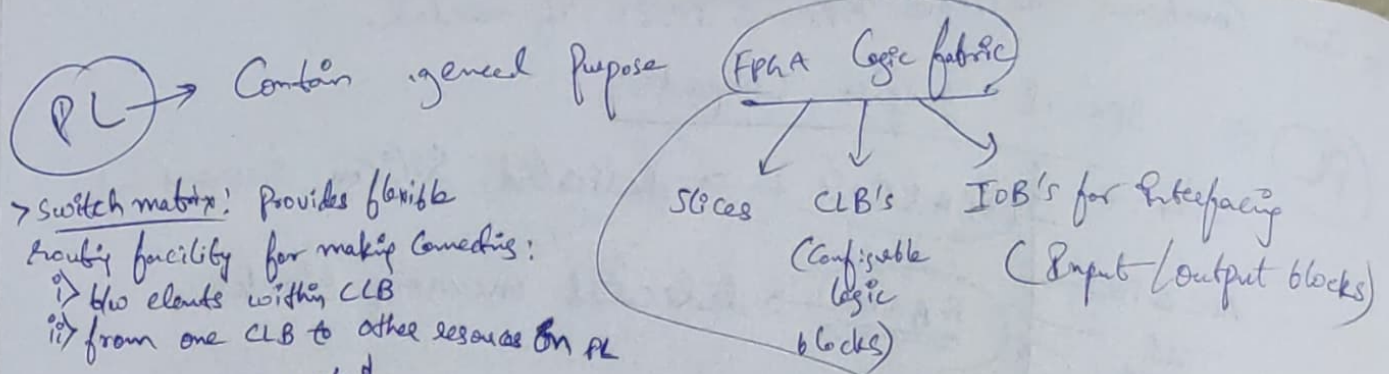
Set of Processing resources
 ↓
 APU
 (Application processing unit)



MMIO is responsible to translate between virtual & physical addresses.

* also has some responsibility for interfacing with PL
 * ensures cache coherency





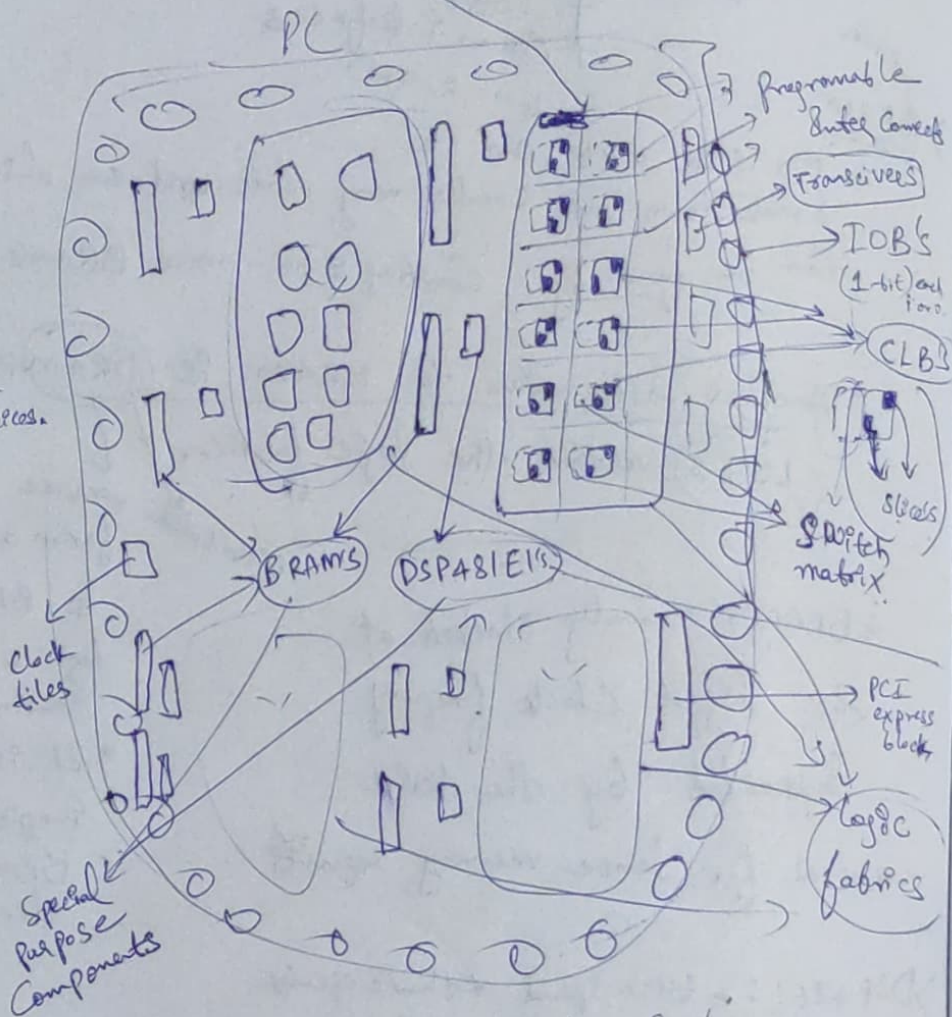
CLB's: small, groups of logic elements that are laid out in a 2D array on PL & are connected to other similar resources via programmable interconnects.

* Each CLB is positioned next to a switch matrix & contains 2 slices.

> Slices: Subunit within CLB, which contains resources for implementing combinational & sequential circuits.

* Slices are composed of:

- 4 LUT,
- 8 FF, &
- other logic.

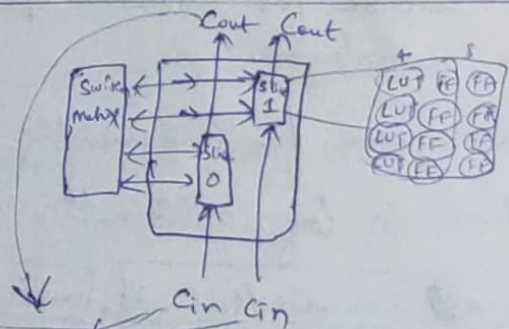


> LUT: a flexible resource capable of implementing

- A logic function of up to 6 i/p's.
- A Small ROM
- A Small RAM
- A Shift register

* LUT's can be combined together to form larger logic functions, memories, shift registers as required

> FF: a sequential circuit implementing a 1 bit reg. with reset facility. One of the FF can typically used to implement a latch



> Carry logic: Intermediate signals to be propagated thru adjacent slices.

* Carry logic has chain of routes & mux to link slices in vertical chain

* Can Combined multiple BRAMs & DSPs if needed.

PL \Rightarrow Special purpose Components:

Clock \rightarrow DSP & REI's \rightarrow dedicated Silicon resources.

ADC & DAC \rightarrow dedicated memory blocks.

JTAG ports

IOB's
Comm interfaces

> Block
> BRAM:

* max size 36kb, can be

break down into smaller memory blocks and can also large capacity memories

can be formed by combining 2 or more BRAMs together.

* Another Alternative to BRAM is DRAM \rightarrow Constructed from the LUT's within the logic fabric.

Distributed * more LUT's required to form a memory of size comparable to BRAM. This results, increased logic & area & there will be routing delays.

* BRAMs normally clocked at the highest clock frequency supported by the device

* used for dense memory requirements

* It is advantageous only to implement small memories using DRAM for resource efficiency & also their placement is flexible.

because they located close to components that interact with them, resulting fast timely response.

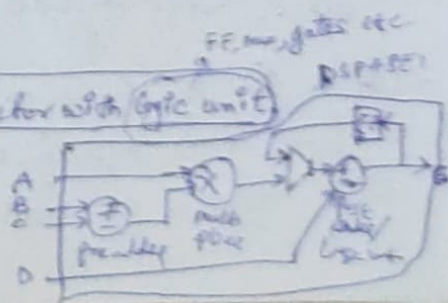
DSP & REI: * High speed arithmetic operators

* LUT's can be used to implement arithmetic operators of any arbitrary length, but are more suitable for arithmetic operators with short word lengths.

* DSP & REI's are for implementing high-speed arithmetic on signals with medium to long arithmetic word lengths.

* Has: Pre-adder/subtractor, multiplier, Post-adder/subtractor with logic unit

* Capable of SIMD processing, implements 2 or + shorter addition/subtraction operations of 24 or 12 bits, respectively



I/O's: (General purpose I/O).

* They are referred as Select I/O Resources, and these are organized into banks of 50 I/O's each.

* Each I/O has 1 pin, which provides the physical connection to the outside world for single 9/10/11 signal.

* I/O banks are categorized as: ① HP (High Performance)
② HR (High Range)

& Support a Variety of I/O standards & voltages.

HP * Limited to 1.8V & are typically used for high-speed interfaces to memory & other chips,

HR * Voltages up to 3.3V and cater for a wider I/O standards.

* Each I/O also includes an IOSERDES resource for programmable conversion b/w parallel & serial data formats of b/w 2-8 bits.

Communication Interfaces: Implemented as quads i.e., groups of 4 individual channels & each has dedicated RX, TX, RX.

* GTX Transceivers. } high speed Comm interface blocks which are embedded into the logic fabric.

↓
dedicated Hard IP blocks (Silicon blocks)

* Supporting Interfaces: PCI express, Serial rapid IO, SCSI, SATA

* In terms of working use IPs & select HW & parameters

Other PL extend Interfaces:

Combinational \rightarrow LUT
Sequential \rightarrow FF

> ADC Block:

* XADC block \rightarrow Hard IP.

Mixed Signal Hardware. } Has 12 separate 12 bit ADC's

* Control of XADC is achieved using the PS-XADC Interface block. Located within PS & programmed from SW executing on APU.

> Clocks:

* PL receives 4 separate clock inputs from PS, and additionally has the facilities to generate and distribute its own clock signals. Independently of the PS.

> JTAG: (programming & debug)

* A set of JTAG ports are provided in the PL section to facilitate configuration and debugging of the PL.

* JTAG supports debugging with both ARM & Xilinx tools.